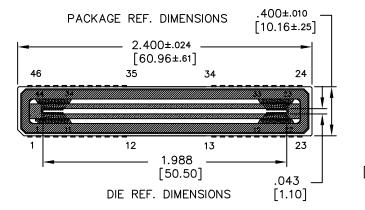
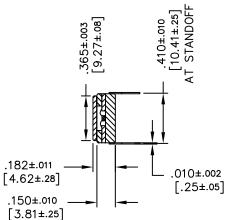
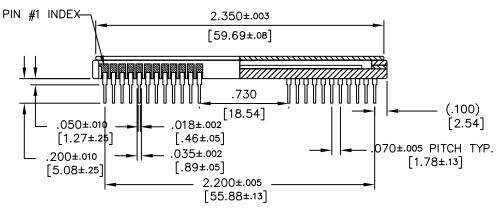
CERAMIC DIP 46, 60.96x10.16

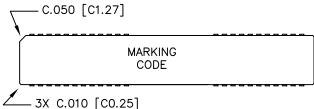
CASE 125BP **ISSUE O**

DATE 03 JUL 2014







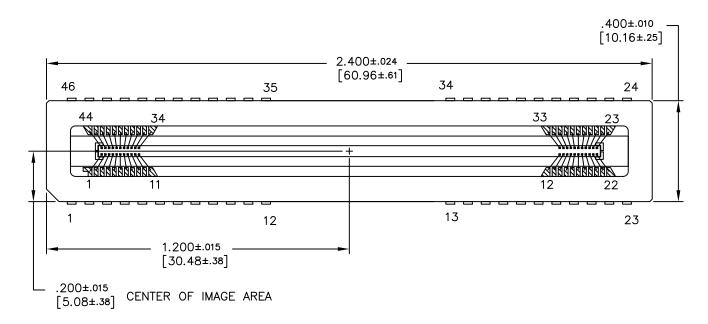


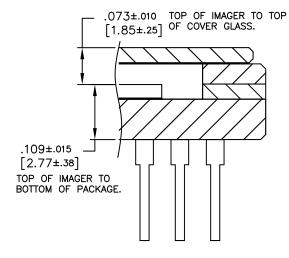
- 1. LEADS 1 AND 23 ATTACHED TO DIE ATTACH METALLIZATION.
- 2. LEADS 12 AND 35 ARE NOT CONNECTED.
- 3. MATERIALS: PINS=ALLOY 42, CERAMIC=BLACK ALUMINA.
 4. COVER GLASS IS MANUALLY PLACED AND VISUALLY ALIGNED OVER PACKAGE - LOCATION ACCURACY IS NOT GUARANTEED.

Dimensions in: Inches [mm]

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NOTES:

- 1. CENTER OF IMAGE AREA IS OFFSET FROM CENTER OF PACKAGE BY (0.00,0.00)mm NOMINAL.
- 2. DIE IS VISUALLY ALIGNED WITHIN +/- 0.75 DEGREE OF ANY PACKAGE CAVITY EDGE.

Dimensions in: Inches [mm]

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